



## Final Product/Process Change Notification

Document #:FPCN22966XM

Issue Date:27 Jul 2021

<b>Title of Change:</b>	Qualification of FS3 Trench IGBT 12inch Technology at Global Foundries in New York, US for Wafer Fab Capacity Expansion.
<b>Proposed First Ship date:</b>	06 Nov 2021 or earlier if approved by customer
<b>Contact Information:</b>	Contact your local ON Semiconductor Sales Office or <a href="mailto:Bokyun.Seo@onsemi.com">Bokyun.Seo@onsemi.com</a>
<b>PCN Samples Contact:</b>	Contact your local ON Semiconductor Sales Office or <a href="mailto:PCN.samples@onsemi.com">&lt;PCN.samples@onsemi.com&gt;</a> . Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
<b>Additional Reliability Data:</b>	Contact your local ON Semiconductor Sales Office or <a href="mailto:Byeongyeop.Lee@onsemi.com">Byeongyeop.Lee@onsemi.com</a>
<b>Type of Notification:</b>	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <a href="mailto:PCN.Support@onsemi.com">PCN.Support@onsemi.com</a>
<b>Marking of Parts/ Traceability of Change:</b>	No change for the marking of parts & Product date code
<b>Change Category:</b>	Wafer Fab Change
<b>Change Sub-Category(s):</b>	Manufacturing Site Addition

**Sites Affected:**

ON Semiconductor Sites	External Foundry/Subcon Sites
ON Semiconductor Aizu, Japan	Global Foundries East Fishkill, New York, United States
ON Semiconductor Bucheon, Korea	

**Description and Purpose:**

This is a Final Change Notification (FPCN) to customers announcing the qualification of additional wafer fabrication facility for FS3 TIGBT technology at Global Foundries in New York, US.

Qualification tests are designed to show that the reliability of the affected devices will continue to meet or exceed ON Semiconductor standards, with no form, fit or functions alterations

	Before Change Description	After Change Description
<b>Wafer FAB site</b>	Bucheon, Korea, AIZU, Japan	Bucheon, Korea, AIZU, Japan, East Fishkill, USA

There is no product marking change as a result of this change.

**Reliability Data Summary:**

QV DEVICE NAME: FGH75T65SHD-F155, FGH75T65SHDT-F155, FGH60T65SHD-F155, FGY160T65SPD-F085

RMS: U78532, U78534, U78535, U78536, U76790, U74188, U74191, U72040

PACKAGE: TQ247

Test	Specification	Condition	Interval	Results
HTRB	JESD22-A108	Ta=175°C, 100_% max rated V	1008 hrs	0/240
HTGB	JESD22-A108	Ta=175°C, 100_% max Vge	1008 hrs	0/240
HTSL	JESD22-A103	Ta=175°C, No bias	1008 hrs	0/240
TC	JESD22-A104	Ta= -55°C to + 150_°C	1000 cyc	0/240
HAST	JESD22-A110	130°C, 85% RH, 18.8psia, bias	96 hrs	0/240
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/240
IOL	ML-STD-750	Ta=25°C, delta Tj=100°C On/Off = 5min	3000 cyc	0/240

**Electrical Characteristics Summary:**

Electrical characteristics are not impacted.

**List of Affected Parts:**

**Note:** Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

Part Number	Qualification Vehicle
FGH60T65SHD-F155	FGH60T65SHD-F155
FGA3060ADF	FGH75T65SHD-F155